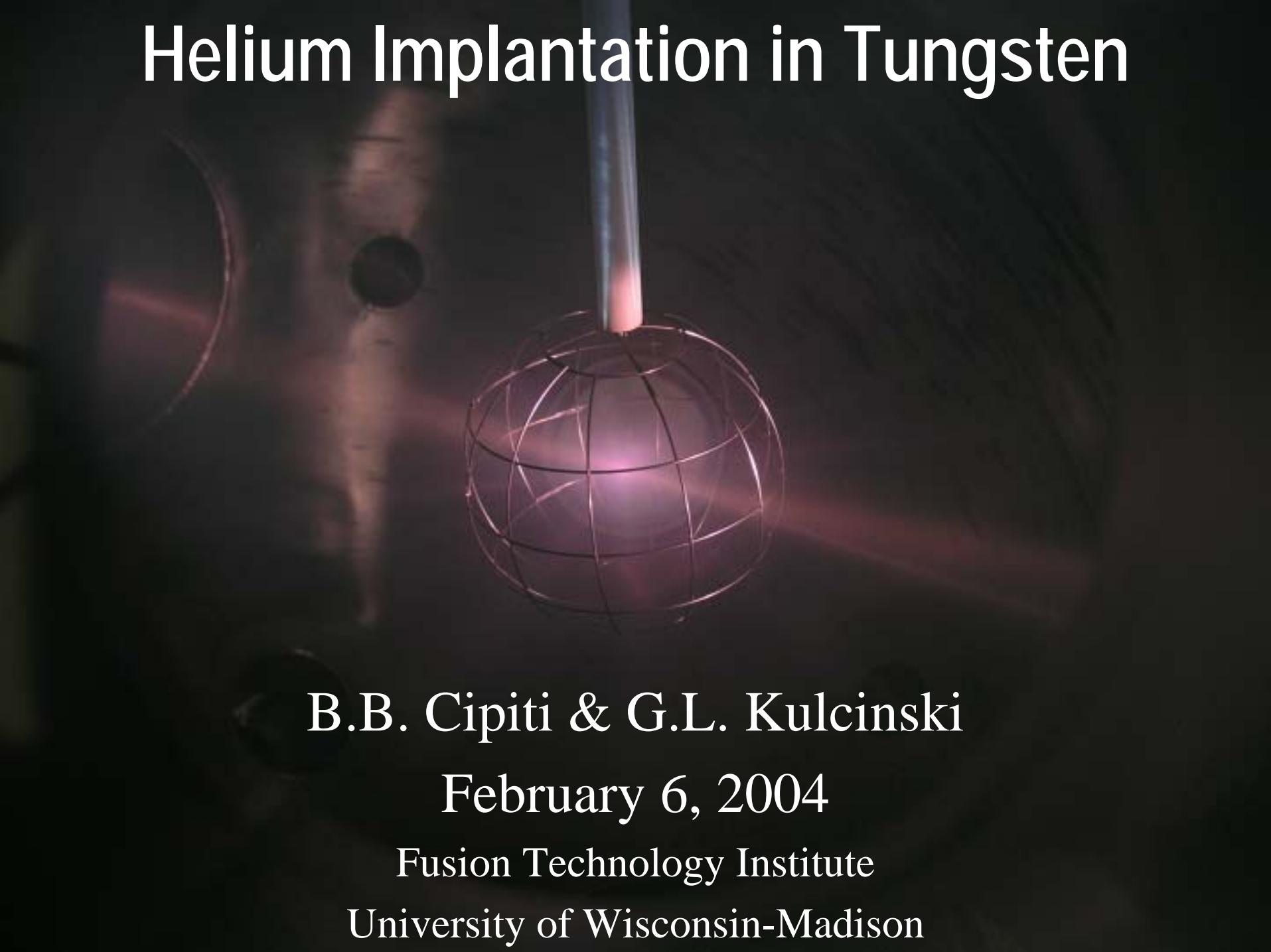


Helium Implantation in Tungsten



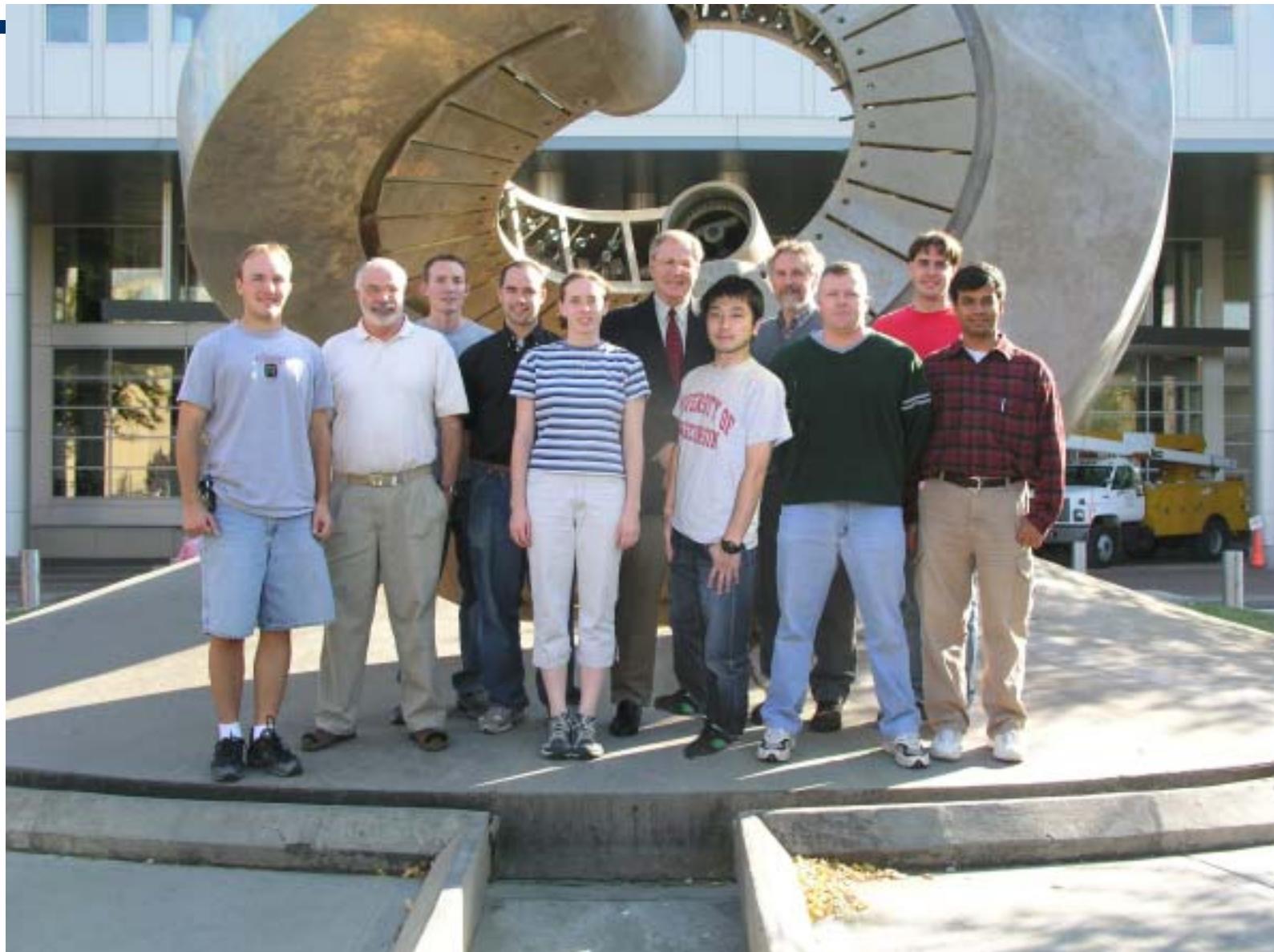
B.B. Cipiti & G.L. Kulcinski

February 6, 2004

Fusion Technology Institute

University of Wisconsin-Madison

The Wisconsin IEC Team

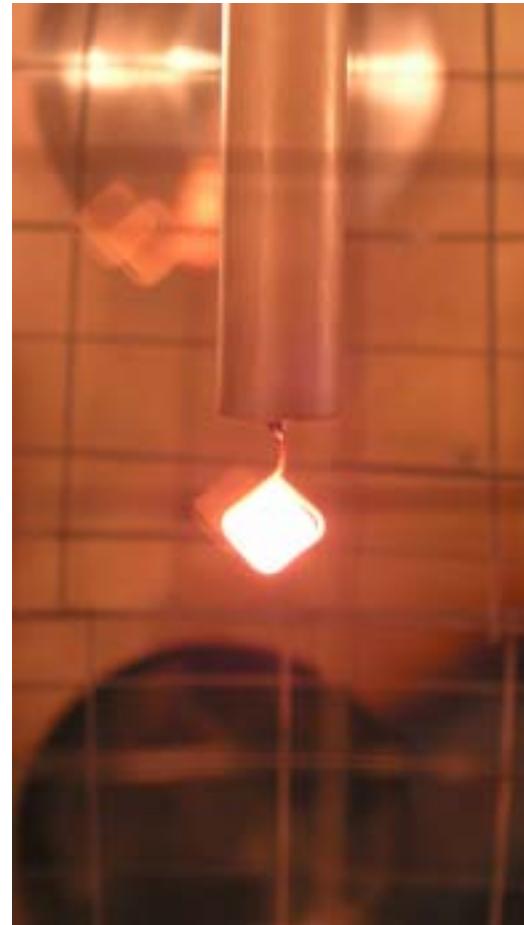


Helium Implantation in Tungsten at High Temperatures at the University of Wisconsin

- ◆ **Purpose:** To determine the effect of helium implantation on the surface morphology of tungsten at high temperatures
- ◆ **Why?** To see if tungsten can serve as a suitable material for the HAPL first wall
- ◆ **How?** Use high energy helium ions to bombard W while it is at temperatures typical of HAPL chamber

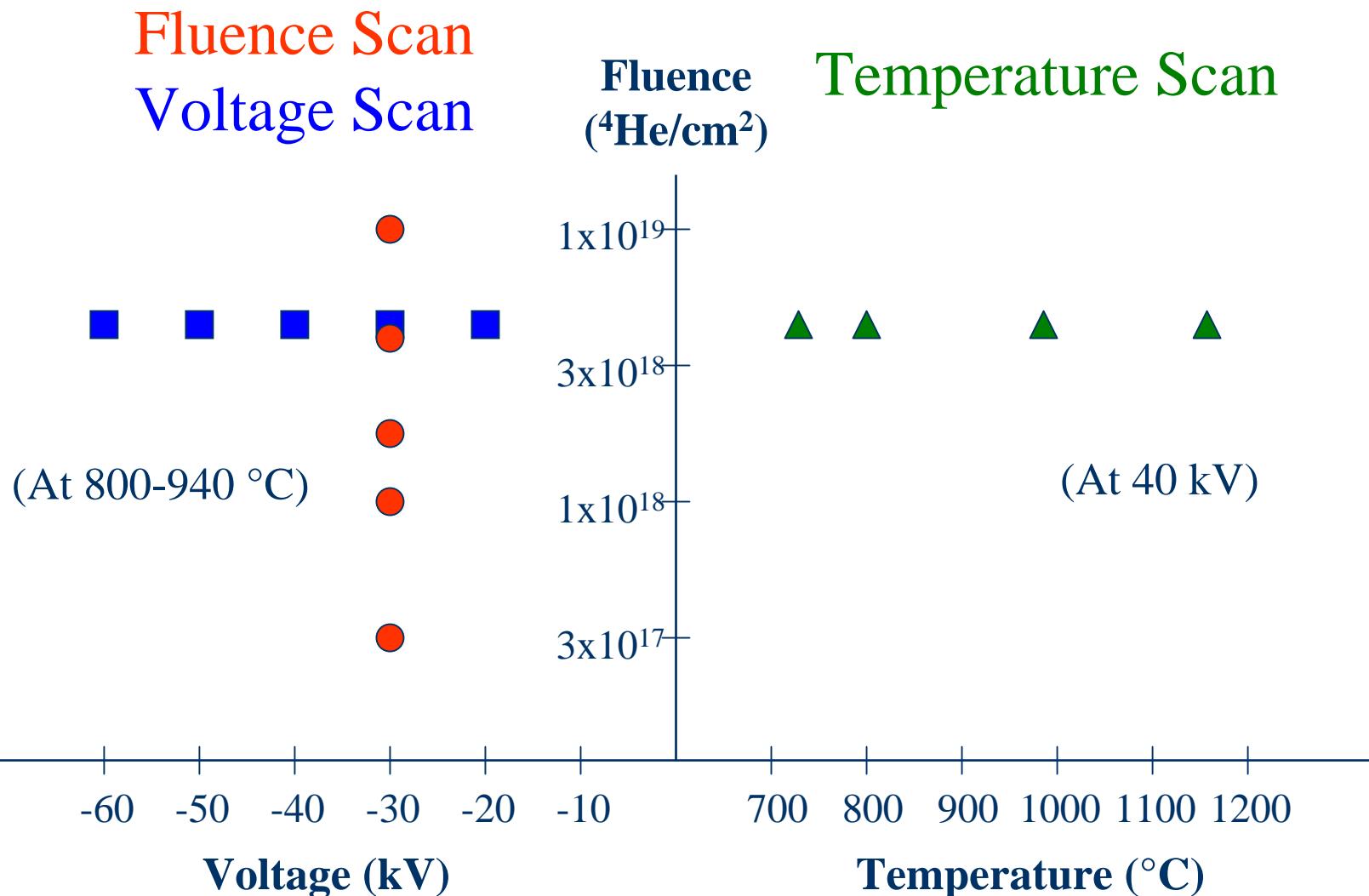


UW IEC Chamber has Capability of High-Temperature Implantation at 10-150 kV



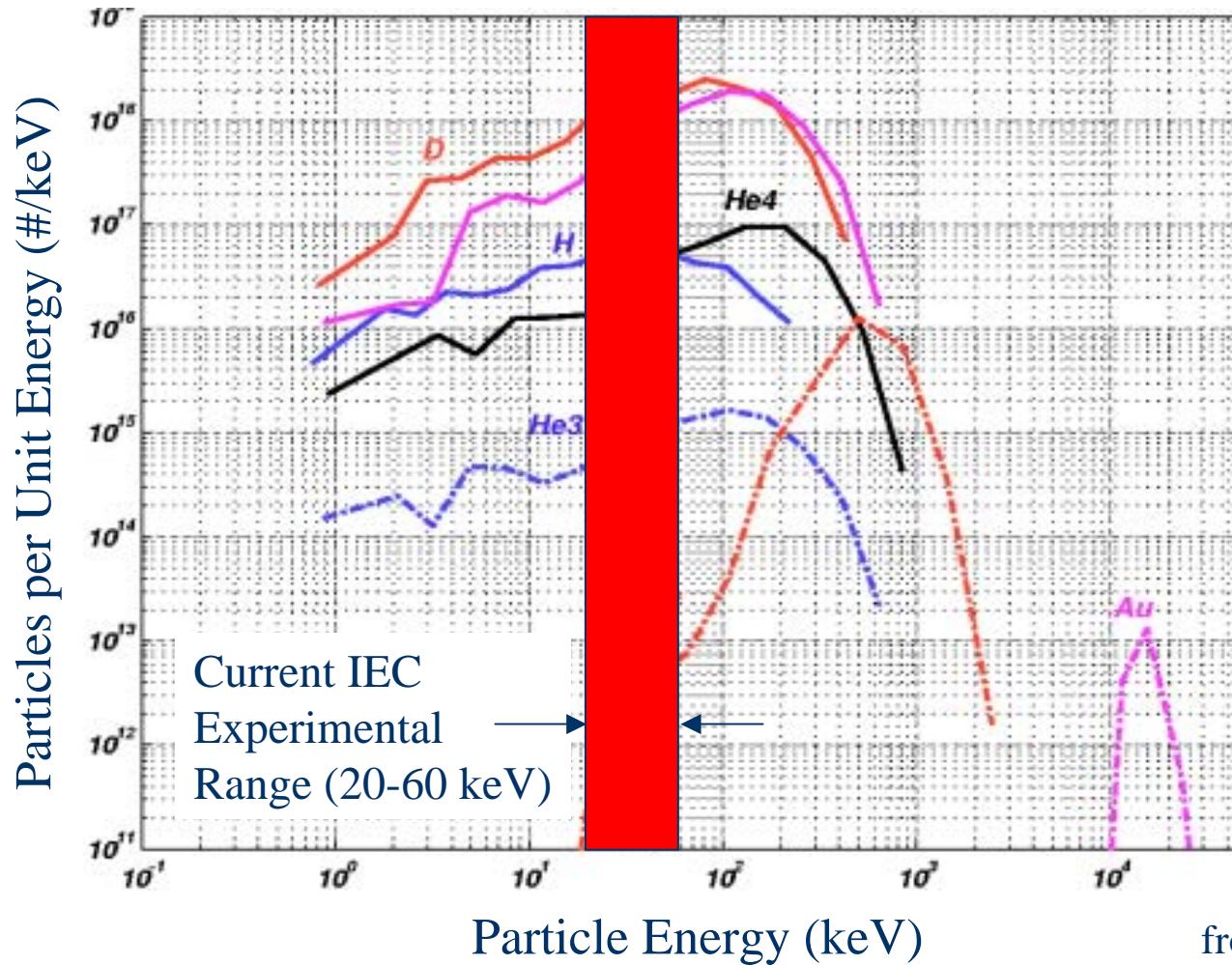
D⁺, 20 kV, 5 mA
2 mtorr, 1100 °C

HAPL Implantation Experiments



Early Implantation Studies Cover a Limited Range of the Helium Energy Spectrum

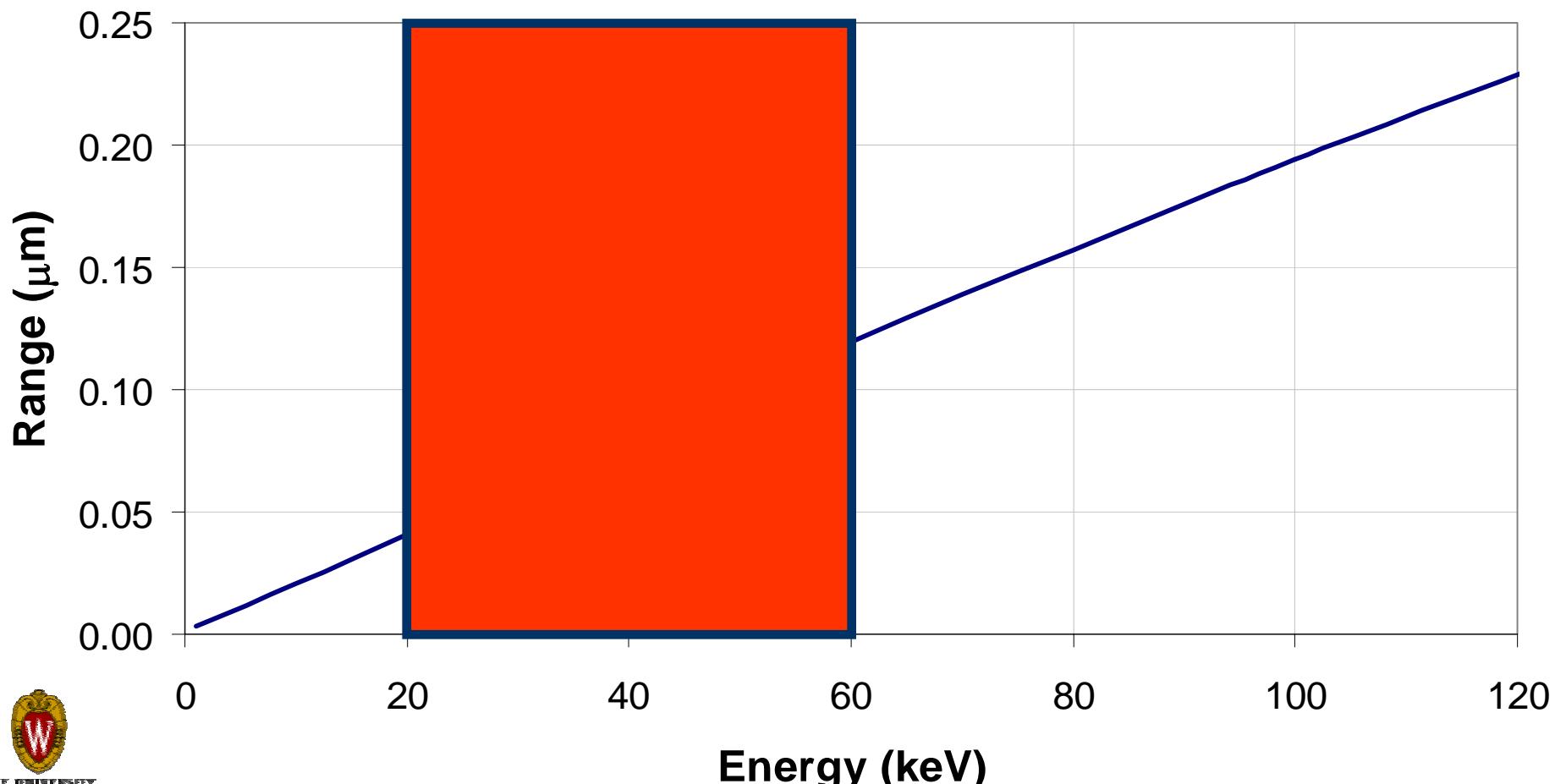
HAPL Debris Ion Energy Spectra



from R. Raffray

The Helium Ions from a HAPL Target Have a Short Range in W

Range of Helium Ions in Tungsten



Threshold for Tungsten Pore Formation

$<1 \times 10^{18}$ He/cm² (30 keV He on W 7x10¹⁵ ions/cm²-s)

As Received

3×10^{17} He/cm²
800 °C

1×10^{18} He/cm²
800 °C

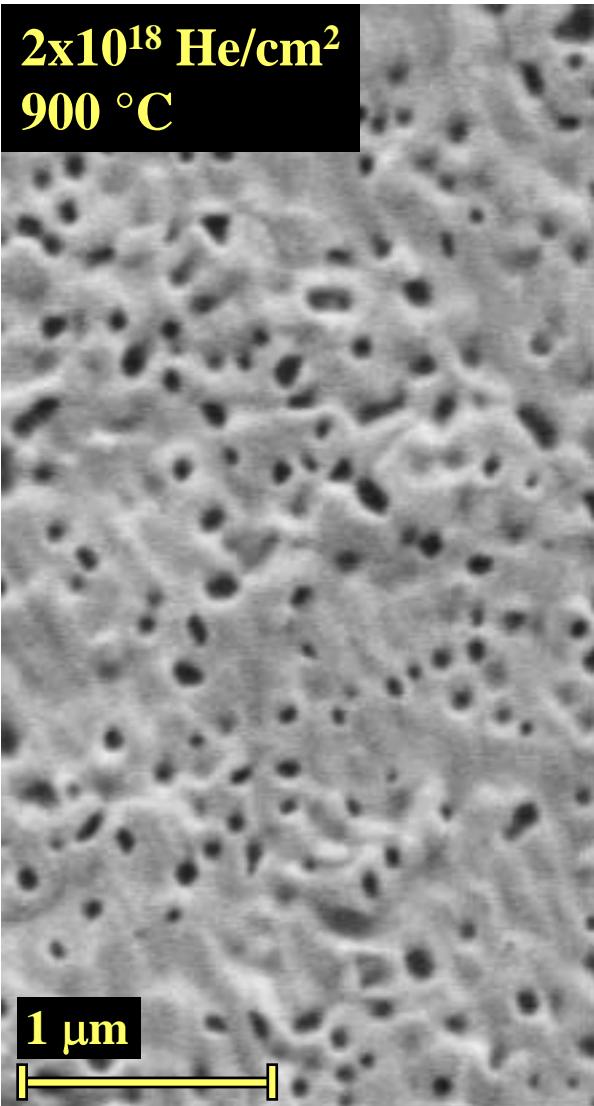
1 μm

1 μm

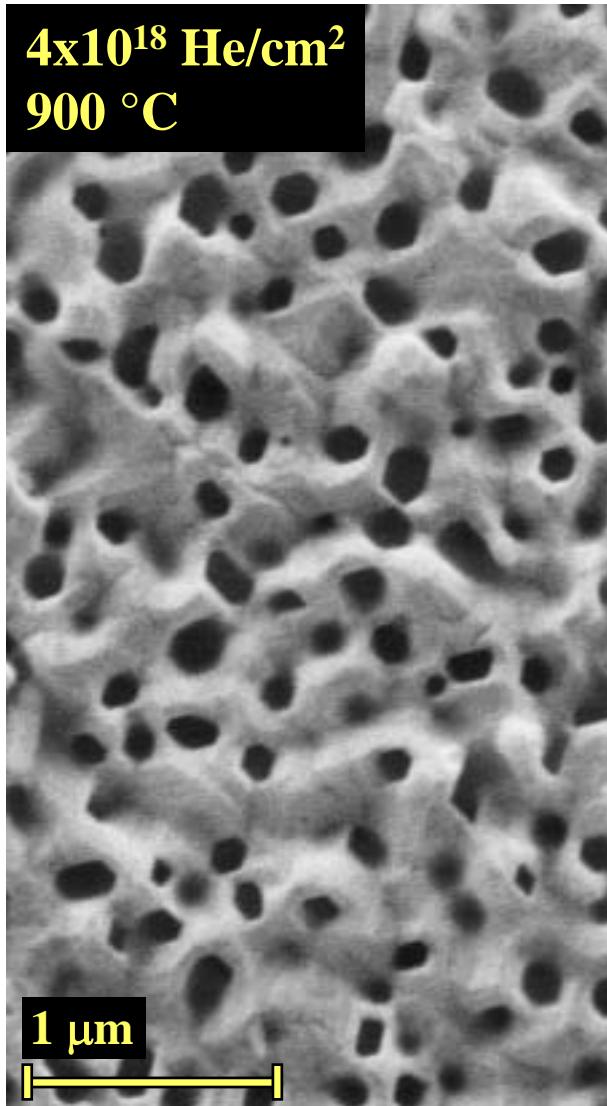
1 μm

Tungsten Pore Structure Stabilizes at $\sim 4 \times 10^{18}$ He/cm² (30 keV He on W-7x10¹⁵ions/cm²-s)

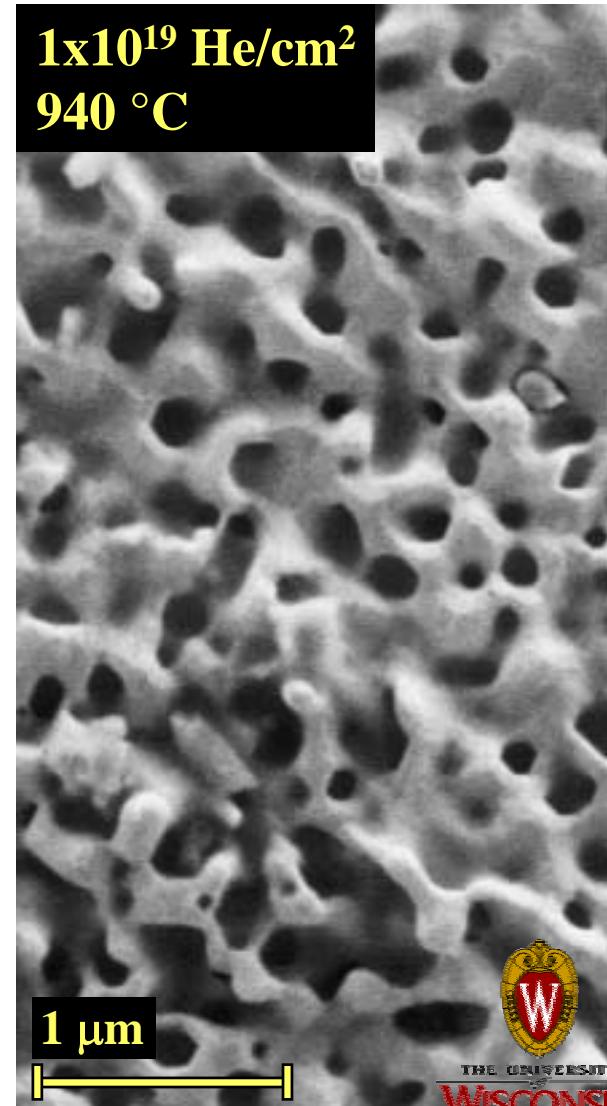
2×10^{18} He/cm²
900 °C



4×10^{18} He/cm²
900 °C



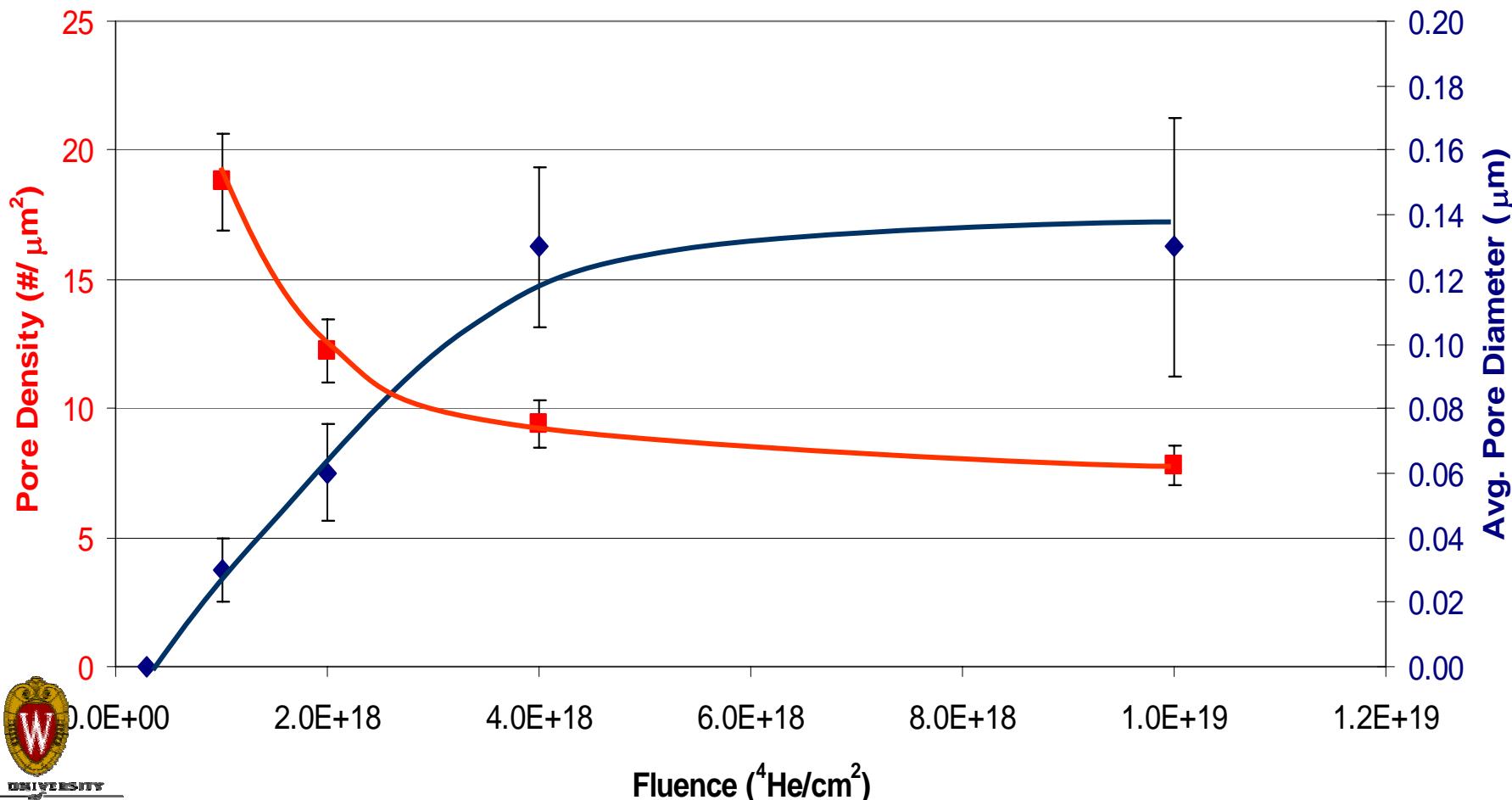
1×10^{19} He/cm²
940 °C



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MADISON

Pore Diameter Increases with Increasing Fluence while Pore Density Decreases

Pore Parameters vs. Helium Fluence
30 keV He on W (800-980 °C)



Pore Size Increases with Temperature

(40 keV He on W 5×10^{18} ions/cm²)

730 °C

2.2×10^{15} He/cm²-s
30 min.

800 °C

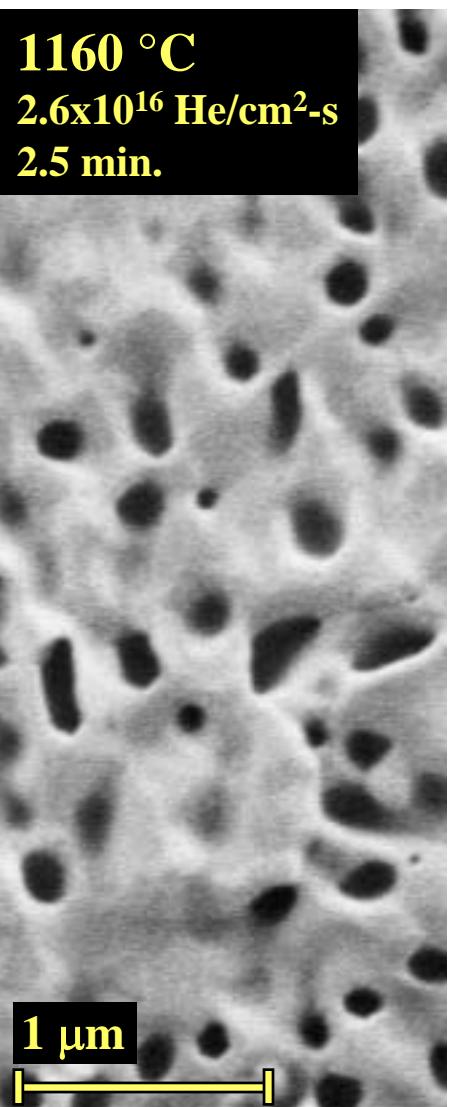
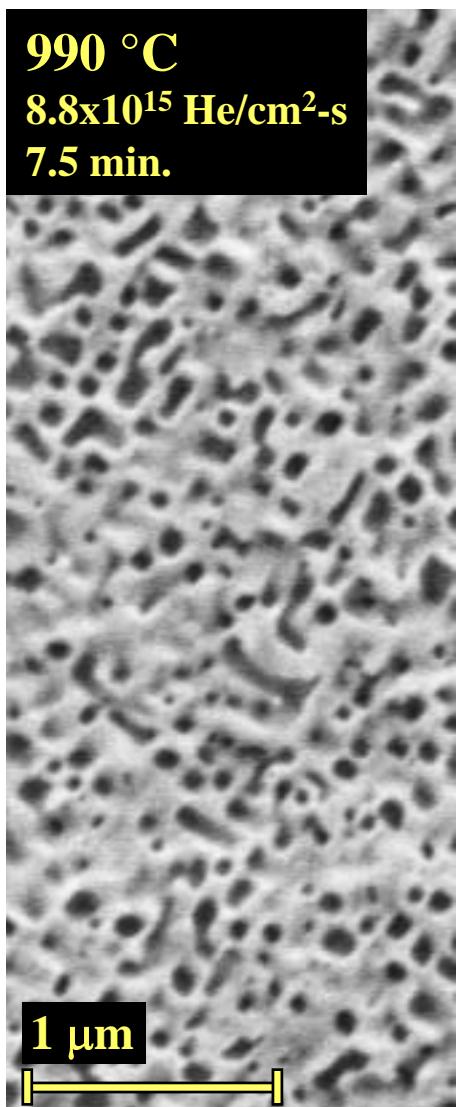
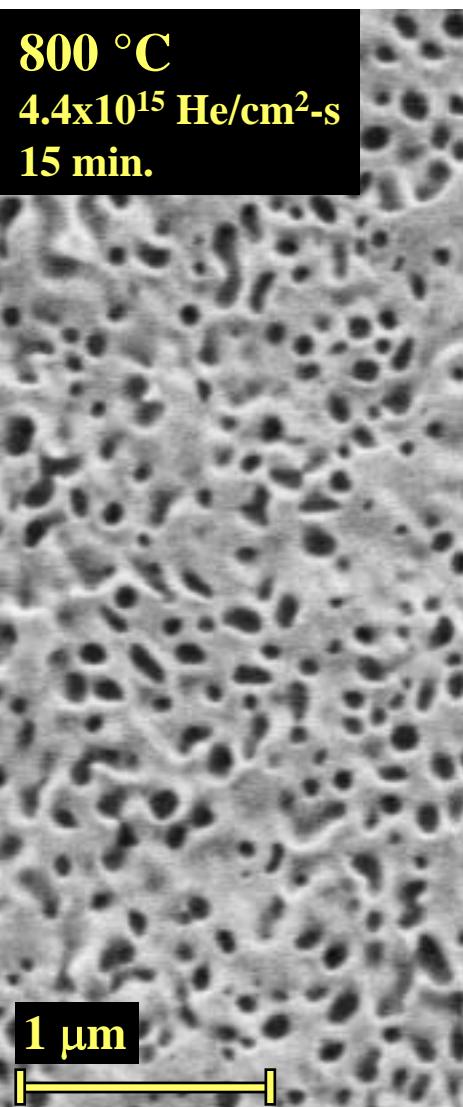
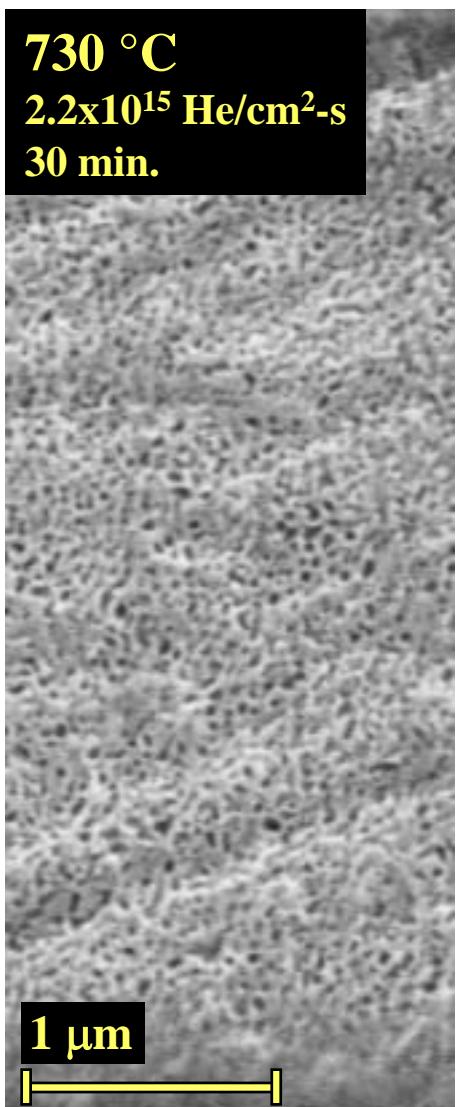
4.4×10^{15} He/cm²-s
15 min.

990 °C

8.8×10^{15} He/cm²-s
7.5 min.

1160 °C

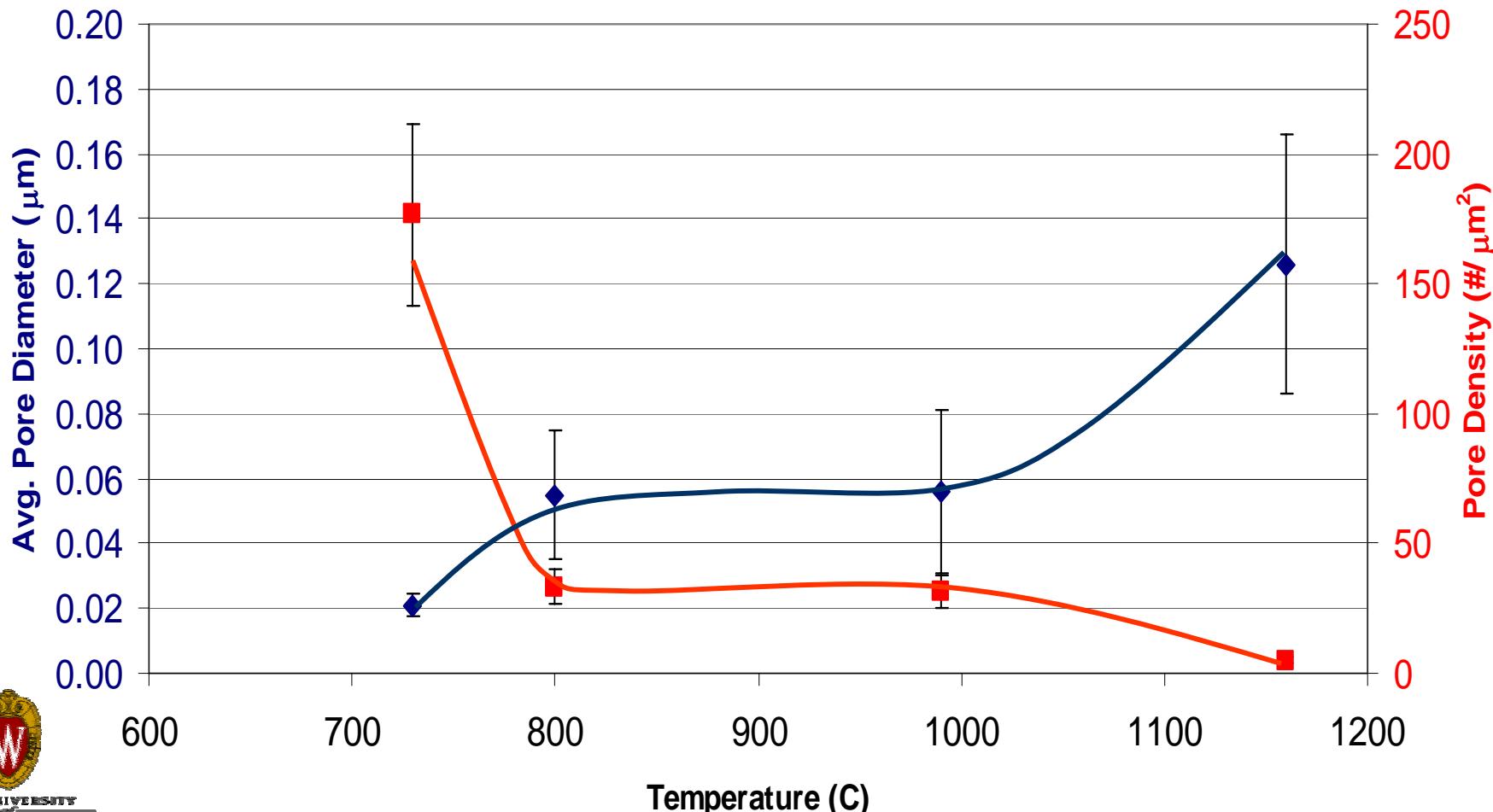
2.6×10^{16} He/cm²-s
2.5 min.



Pore Diameter Increases with Increasing Temperature while Pore Density Decreases

Pore Parameters vs. Temperature

40 keV, 5×10^{18} $^4\text{He}/\text{cm}^2$ on W



Conclusions

- ◆ Threshold for pore formation in tungsten at 800 °C is $< 1 \times 10^{18}$ He/cm² (30 keV)
- ◆ Pore diameter saturates at 0.15 μm and density saturates at 7 pores/μm² for 30 keV implantation at $\sim 5 \times 10^{18}$ He/cm²
 - It might suggest that by 5×10^{18} @ HAPL wall temperatures, an equilibrium surface condition will be attained
- ◆ Pore diameter increases by a factor of 6 and density decreases by factor of 35 when temperature increases from 730 to 1160 °C at 40 keV implantation
- ◆ Implantation energies from 20 to 60 keV showed no substantial difference in surface structure

Future Work

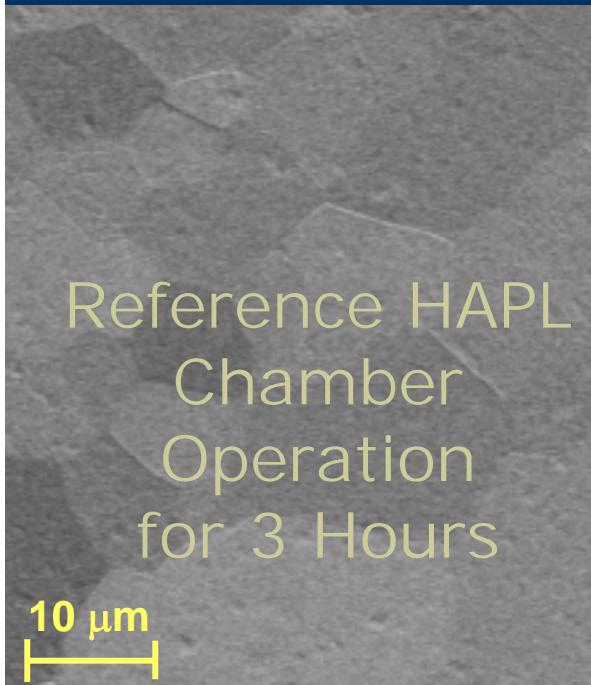
- ◆ Repeat experiments with simultaneous deuterium implantation
- ◆ Determine density depth profile of helium in tungsten using elastic recoil detection
- ◆ Push towards higher energies (~ 100 keV)
- ◆ Consider implantation in W-Re alloy



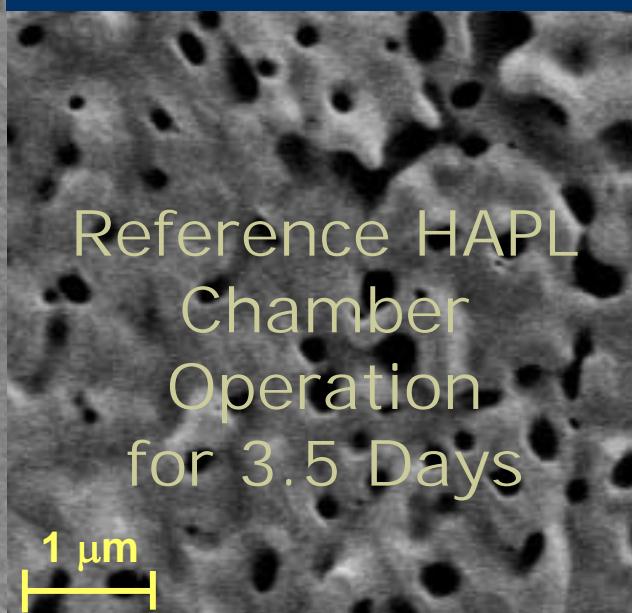
End of Talk

Preliminary Conclusions

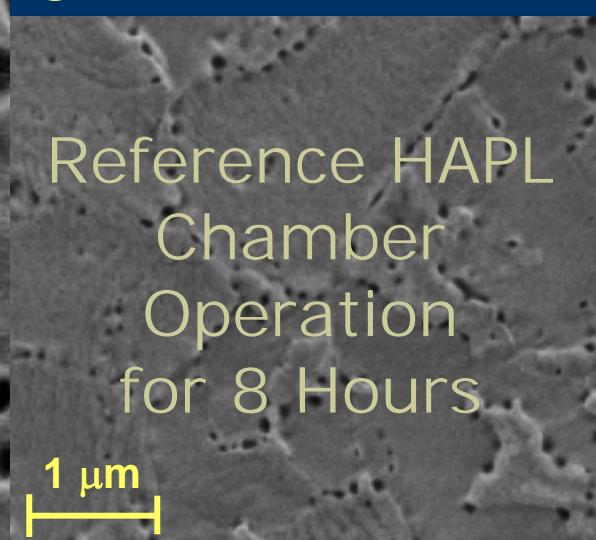
At 1100-1300 °C,
 2×10^{19} D⁺/cm²
implantation
produced no
blistering



At 1200 °C,
 6×10^{18} He⁺/cm²
implantation
produced
“pinhole” porous
surface structure

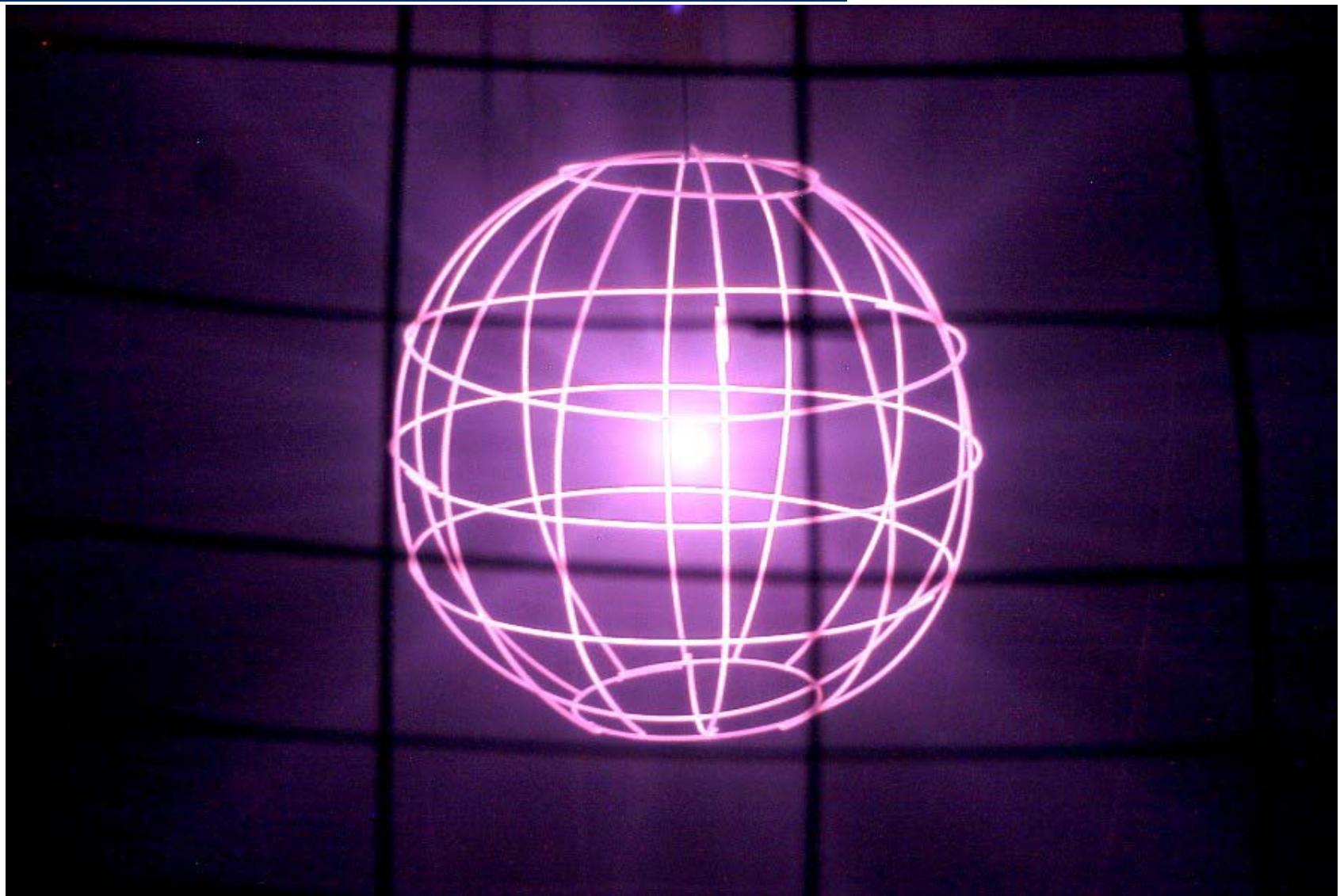


At 1100 °C,
 6×10^{17} He⁺/cm²
implantation
produced helium
bubbles that
decorate the
grain boundaries



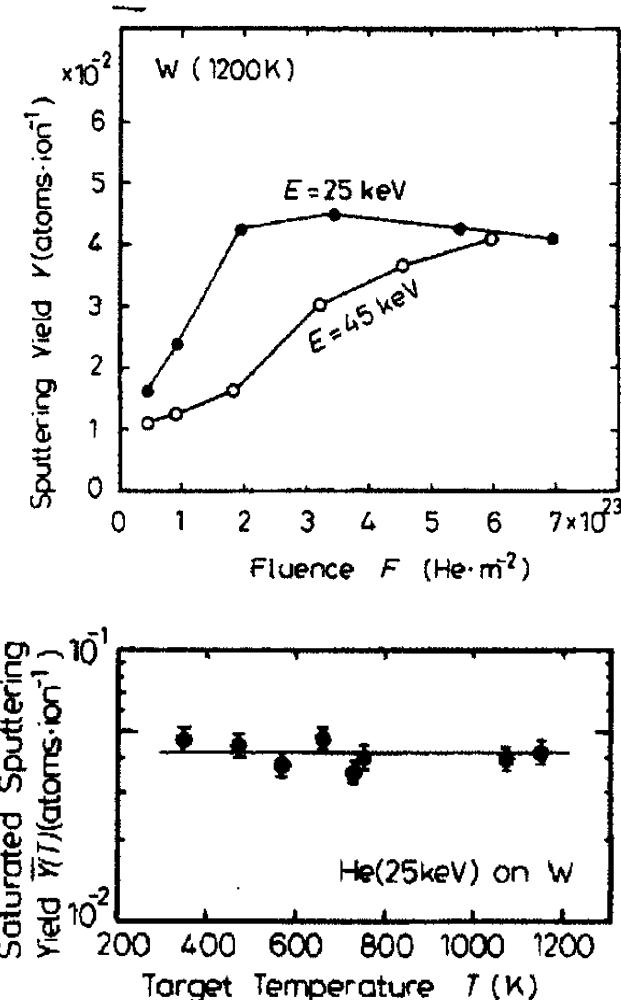


Steady State D-³He Fusion in the UW IEC Device



Helium Sputtering Yield on Tungsten

- ◆ Sputtering yield saturates at ~ 0.04 for 25 keV helium on tungsten at 1200 K
- ◆ Saturated yield is constant with temperature
- ◆ Assuming 1.7×10^{18} $^4\text{He}/\text{cm}^2/\text{day}$ (on the HAPL chamber), a sputtering yield of 0.04 would result in a loss of $3.9 \mu\text{m}/\text{year}$ (This is only due to the helium)



Helium Implantation in Tungsten

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